

CONNECTORS

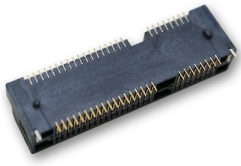
Operation: 0.80MM PITCH MINI-PCI EXPRESS / [MINI-PCI E 连接器]

REACH

RoHS Compliant

LTEM NO.: PCIE-52P□□H

(L29.9mm × W8.2mm / 52 CIRCUITS WITH FITTING NAILS)



Technical parameter

PROJECT	LEVEL	A [better product]	
	Contact Rating	0.5A Per PIN / 50V DC	
Electrical Properties	Initial Contact Resistance	50mΩ min.	50mΩ max.
	Insulation Resistance	500MΩ min.	
Durable Performance	Withstand Voltage	300V AC for 1 minute	300 V AC for 1 minut
	There No Load	200 Cycle	
	Rated Load	100 Cycle	
	Storage temp.	-40℃~+85℃ (Operating Temp:)	

表面贴装 SMT

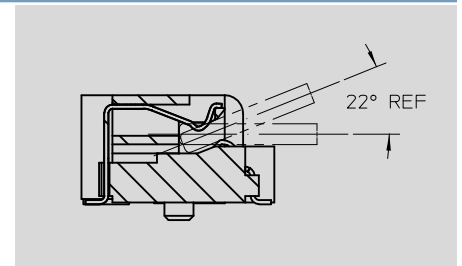
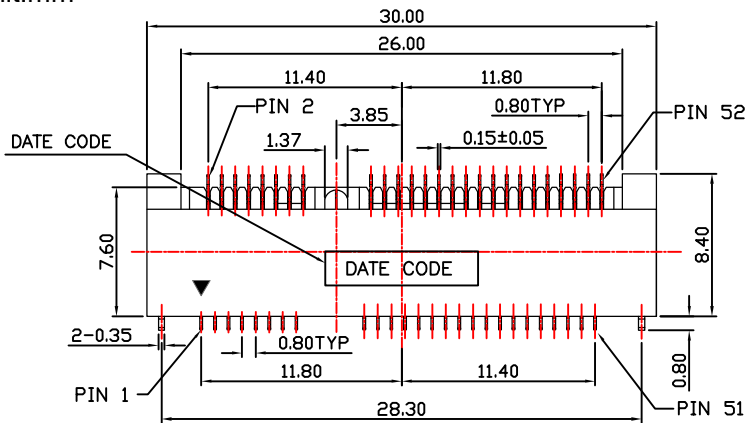
側向導入 LATERAL

精密部品 NICETY

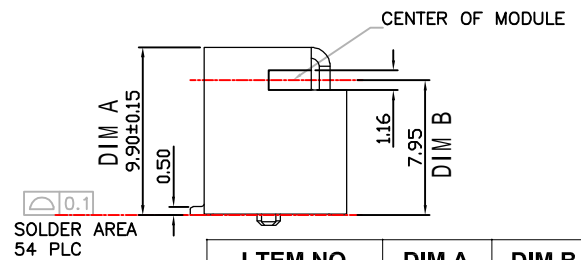
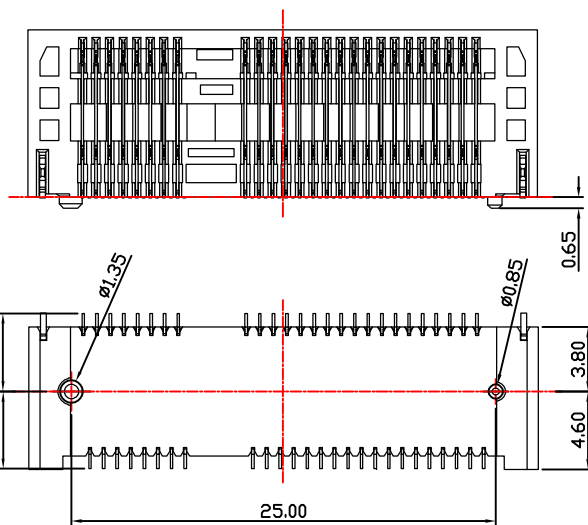
可靠 STABILIZE

適合環保 RoHS

Unit:mm



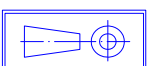
DECIMALS	ANGLES
.X : ±0.25	X.° : ±1.5°
.XX : ±0.15	XX.° : ±1.0°
.XXX : ±0.10	XXX.° : ±0.5°



LTEM NO	DIM A	DIM B
PCIE-52P40H	4.0mm	2.05 mm
PCIE-52P52H	5.2mm	3.25 mm
PCIE-52P56H	5.6mm	3.65 mm
PCIE-52P70H	7.0mm	5.05 mm
PCIE-52P80H	8.0mm	6.05 mm
PCIE-52P90H	9.0mm	7.05 mm
PCIE-52P99H	9.9mm	7.95 mm

Material declaration

No.	NAME	MATERIAL	DESCRIPTION
① A	HOUSING 基座	THERMOPLASTIC LCP MG305	UL 94V-0, COLOR: BLACK;
② B	TERMINAL 接触端子	COPPER ALLOY 【G/F】 磷铜合金 C5210	2.0 μm Ni PLATED OVERALL; 0.25 μm Au PLATED CONTACT AREA; GOLD FLASH ON SOLDER AREA.
③ C	HOLDDOWN 固定端子	COPPER ALLOY 黄铜 C2680	0.25 μm Ni PLATED OVERALL;



Operating Force

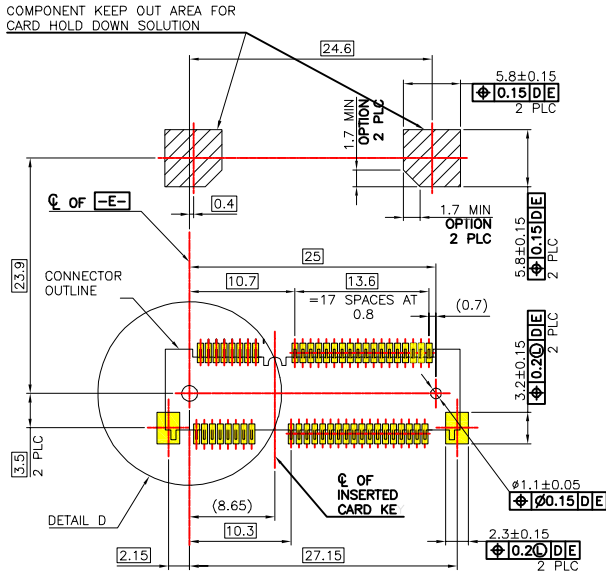
Inward
Exiting

2.3Kgf MAX.
2.3Kgf MAX.

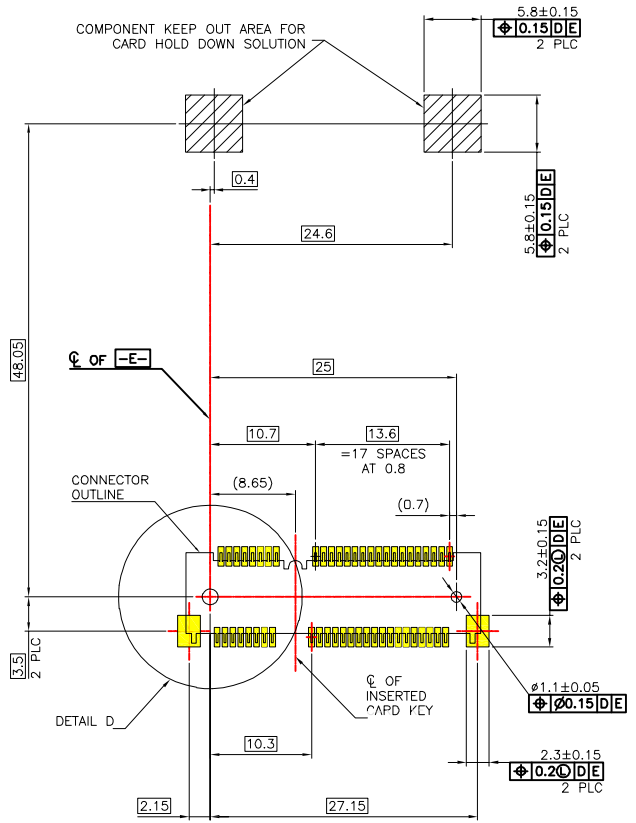
Solder-ability (Max.)

IR Reflow: 255°C, 5sec.

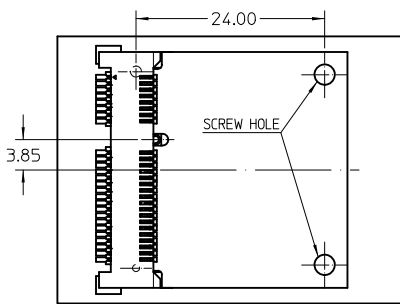
Manual: 350°C, 3sec.



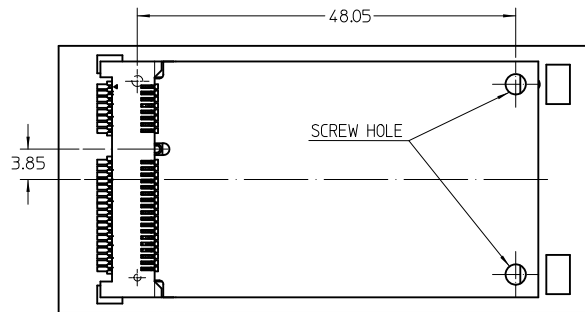
-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR HALF CARD CONNECTOR
(TOP VIEW)



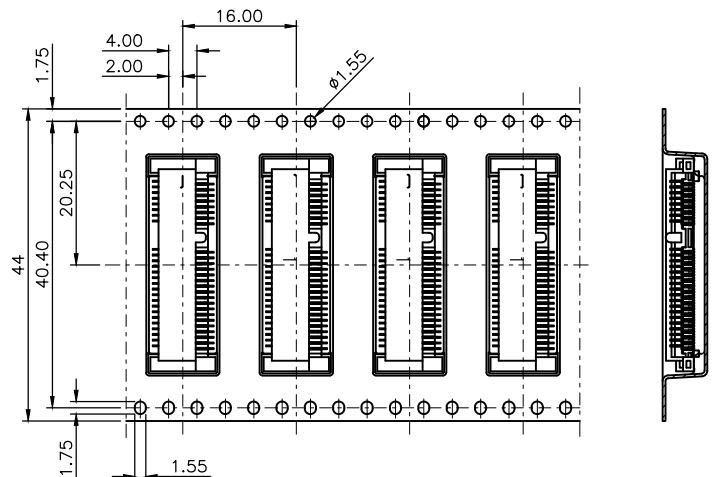
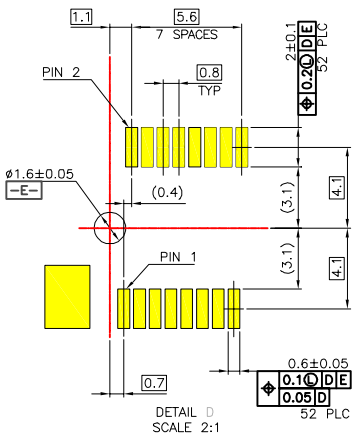
-D- IS THE TOP SURFACE OF PCB.
RECOMMENDED P.C. BOARD PATTERN LAYOUT
FOR FULL CARD CONNECTOR
(TOP VIEW)



HALF-MINI CARD
APPLICATION
SCHEMATICS



FULL-MINI CARD
APPLICATION
SCHEMATICS



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